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Liu et al.

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(54) **MULTI-FIN FINFET DEVICE INCLUDING
EPITAXIAL GROWTH BARRIER ON
OUTSIDE SURFACES OF OUTERMOST FINS
AND RELATED METHODS**

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H01L 29/417 (2006.01)

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H01L 29/0847 (2013.01); **H01L 29/41783**
(2013.01); **H01L 29/66795** (2013.01); **H01L**
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(58) **Field of Classification Search**

USPC 257/365, 401, 619, E29.028, E29.259,
257/E29.264, E29.267

See application file for complete search history.

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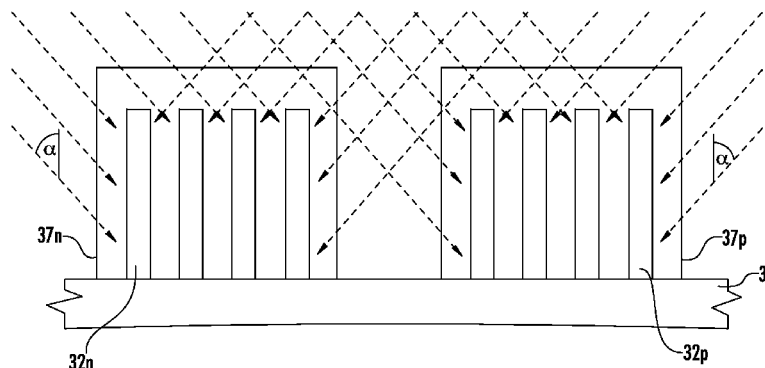
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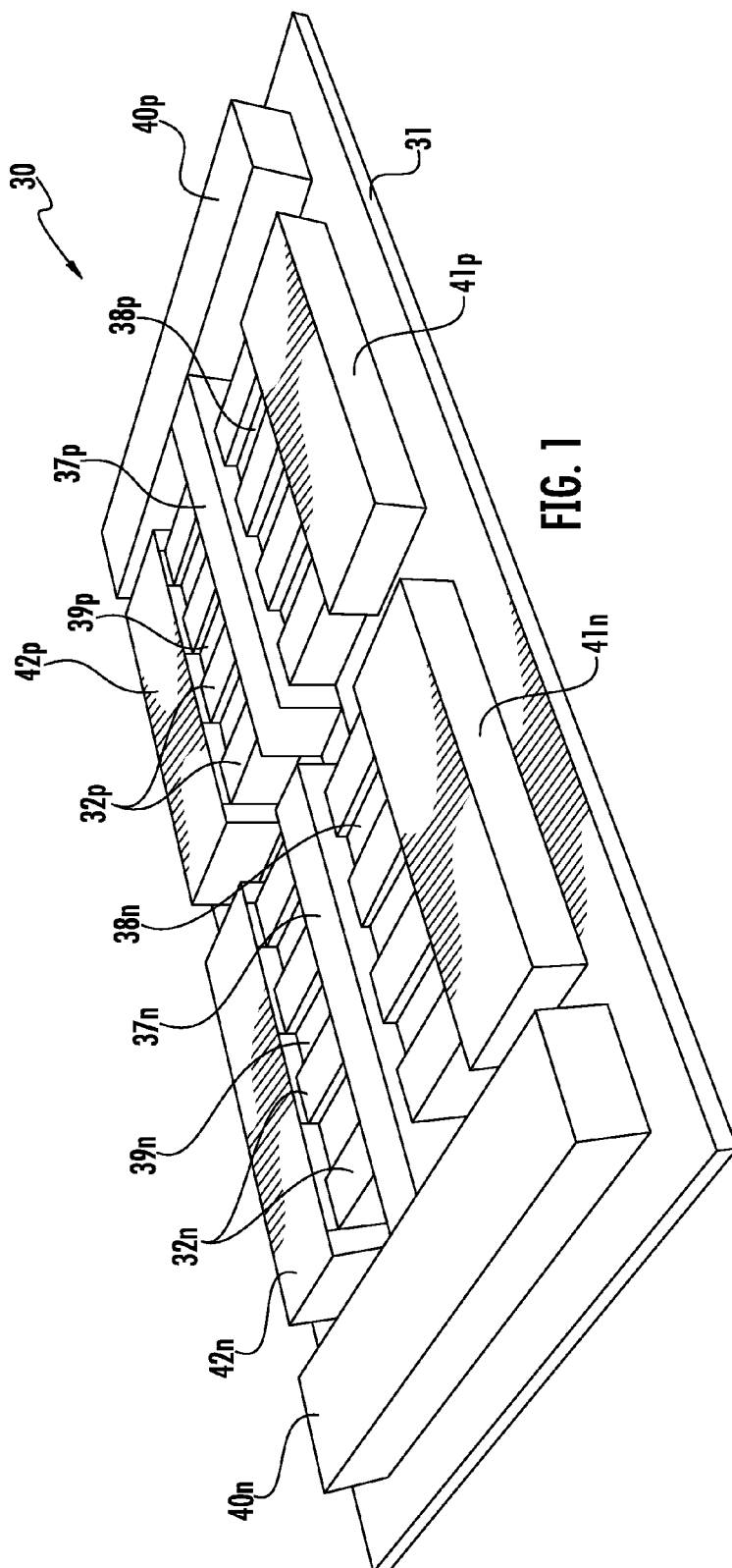
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(57) **ABSTRACT**

A multi-fin FINFET device may include a substrate and a
plurality of semiconductor fins extending upwardly from the
substrate and being spaced apart along the substrate. Each
semiconductor fin may have opposing first and second ends
and a medial portion therebetween, and outermost fins of the
plurality of semiconductor fins may comprise an epitaxial
growth barrier on outside surfaces thereof. The FINFET may
further include at least one gate overlying the medial portions
of the semiconductor fins, a plurality of raised epitaxial semi-
conductor source regions between the semiconductor fins
adjacent the first ends thereof, and a plurality of raised epi-
taxial semiconductor drain regions between the semiconduc-
tor fins adjacent the second ends thereof.

12 Claims, 6 Drawing Sheets





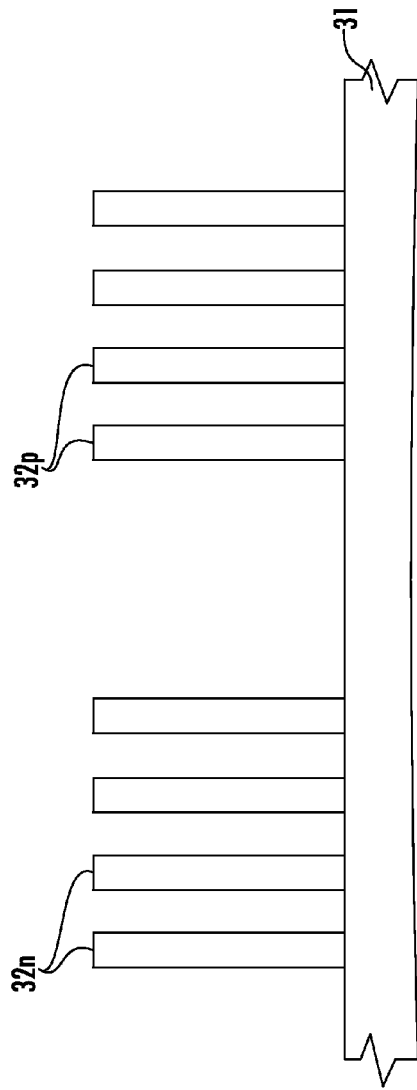


FIG. 2A

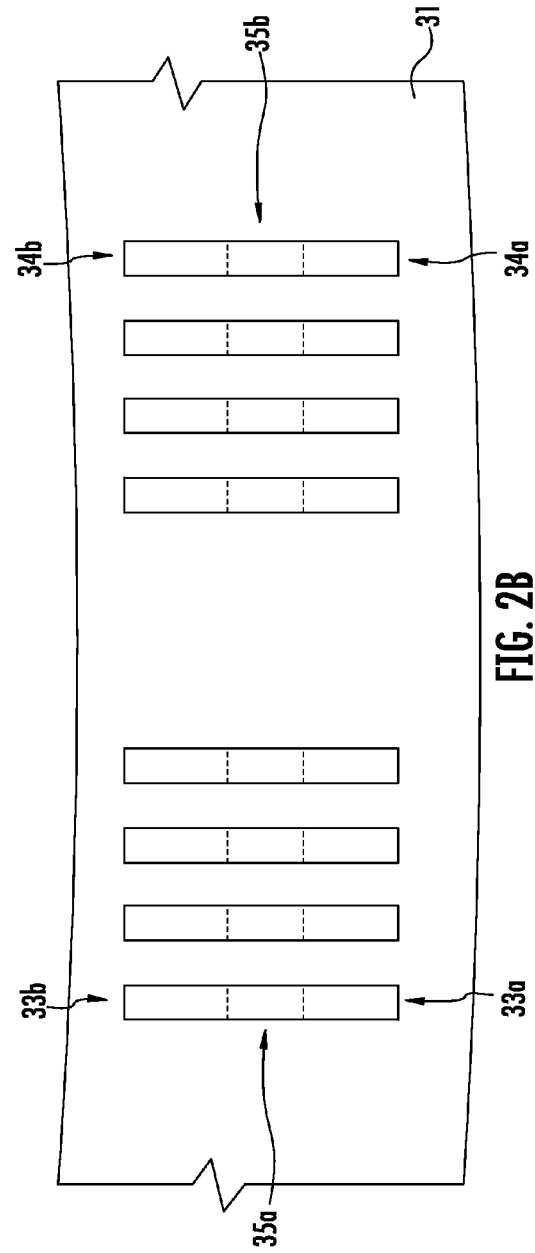
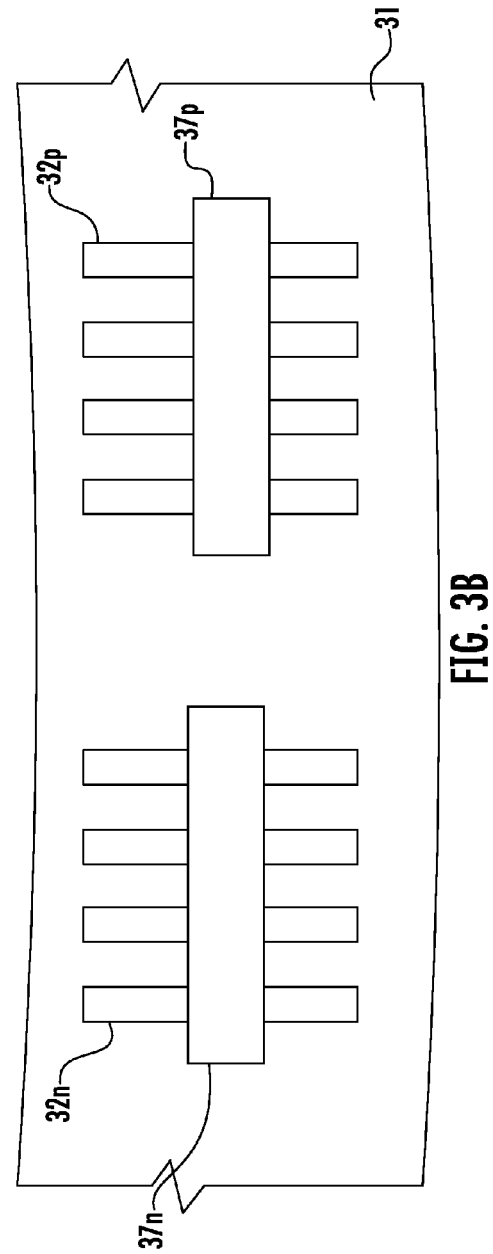
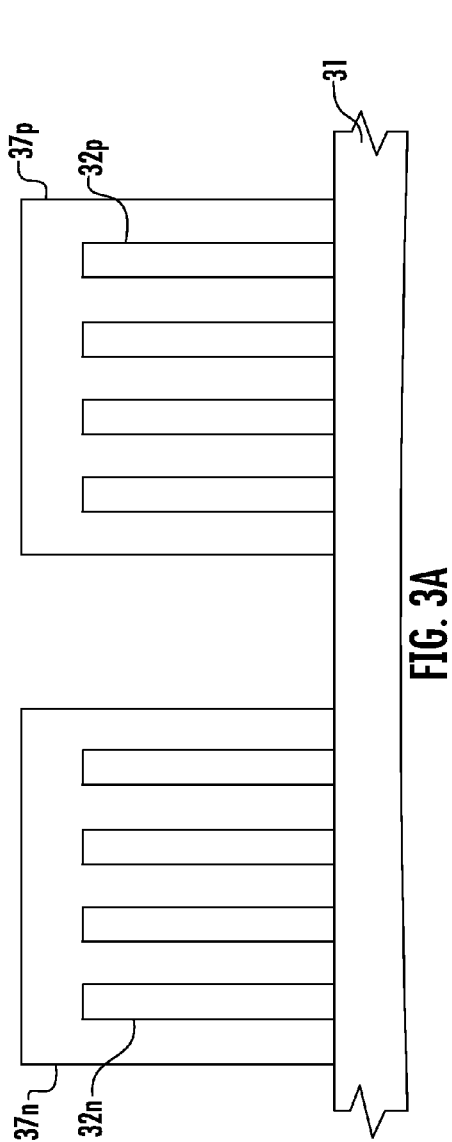
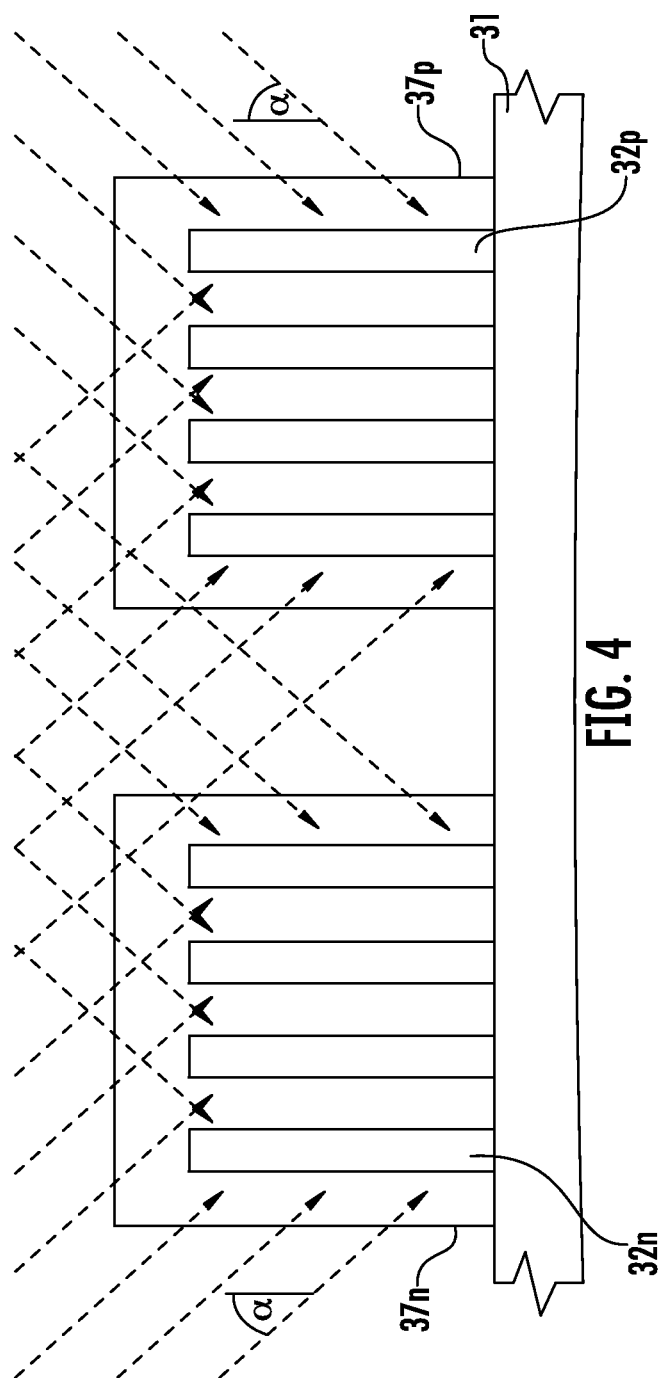


FIG. 2B





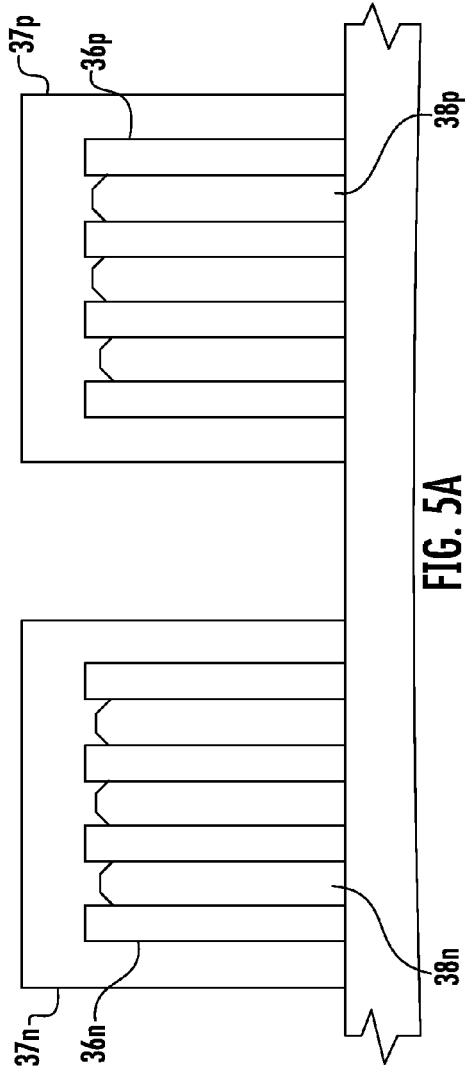


FIG. 5A

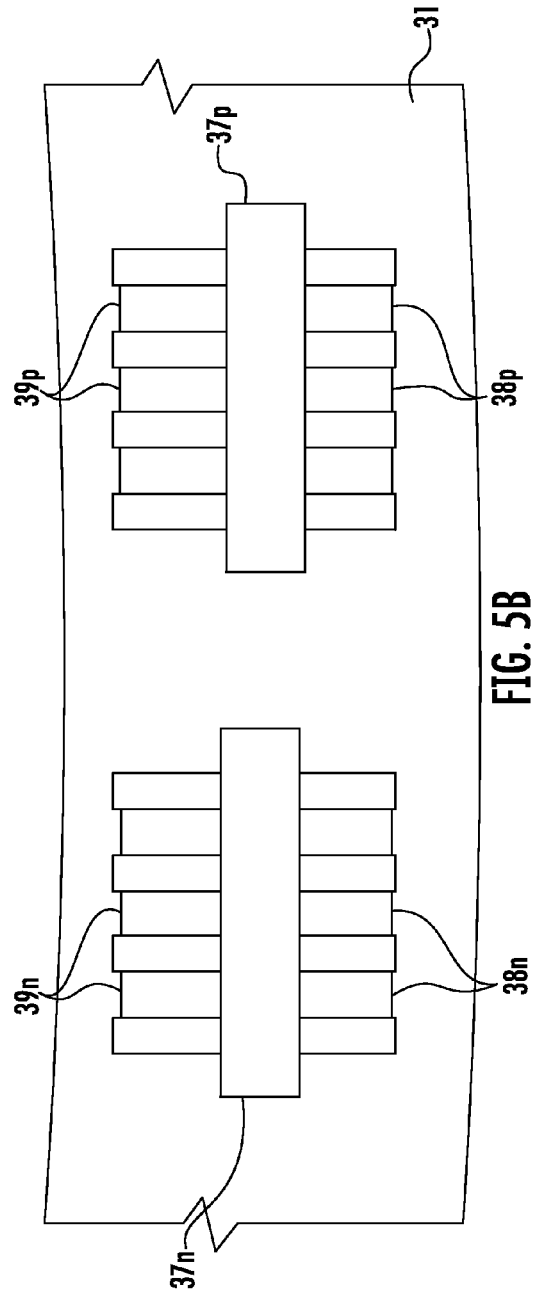


FIG. 5B

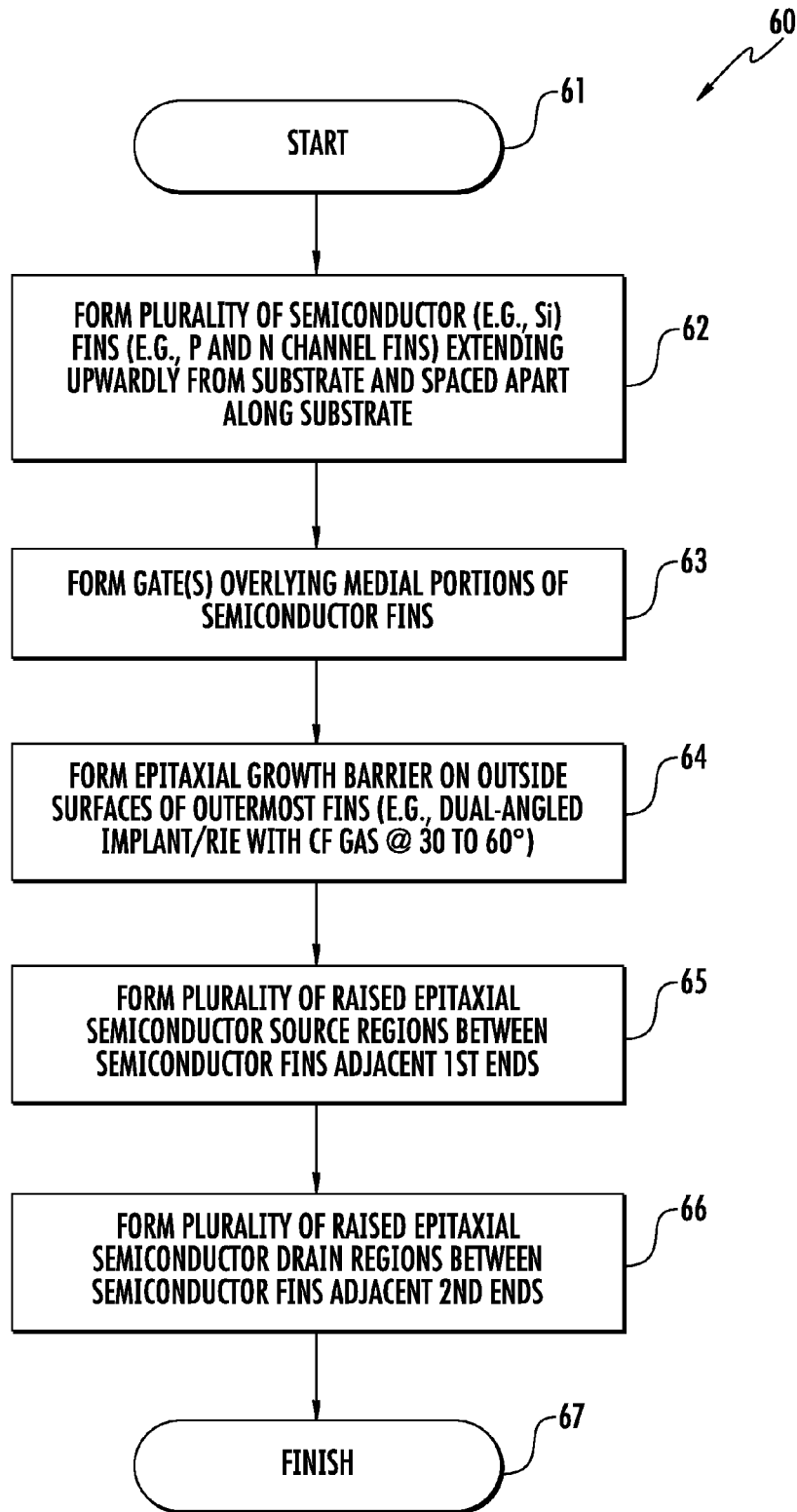


FIG. 6

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MULTI-FIN FINFET DEVICE INCLUDING EPITAXIAL GROWTH BARRIER ON OUTSIDE SURFACES OF OUTERMOST FINS AND RELATED METHODS

FIELD OF THE INVENTION

The present invention relates to the field of electronic devices, and, more particularly, to semiconductor devices and related methods.

BACKGROUND OF THE INVENTION

Semiconductor device technologies continue to evolve, providing higher chip density and operating frequencies. Fin-type field-effect transistors (FINFETs) are one type of transistor technology that is being used to help provide desired device scaling while maintaining appropriate power consumption budgets.

U.S. Pat. Pub. No. 2010/0203732 discloses a FINFET device and related method, in which each FINFET may have a width of sub-lithographic dimension. The method includes forming a mask having a plurality of openings atop a semiconductor-containing layer which is located on a substrate. An angled ion implantation is then performed to introduce dopants to a first portion of the semiconductor-containing layer, wherein a remaining portion that is substantially free of dopants is present beneath the mask. The first portion of the semiconductor-containing layer containing the dopants is thereafter removed selective to the remaining portion of semiconductor-containing layer that is substantially free of the dopants to provide a pattern. The pattern is then transferred into the substrate to provide a fin structure having a width of sub-lithographic dimension.

Another type of FINFET device is the multi-fin FINFET. This device typically includes a plurality of spaced apart semiconductor fins with a tri-gate that overlies the fins. The effective gate width of a FINFET is $2nh$, where n is the number of fins and h is the fin height. Thus, wider transistors with higher on-currents may be obtained by using multiple fins. Yet, higher numbers of fins may result in more complicated devices structures that can pose challenges to fabricate.

SUMMARY OF THE INVENTION

In view of the foregoing background, it is therefore an object of the present invention to provide a multi-fin FINFET device that is reliable and readily fabricated.

This and other objects, features, and advantages in accordance with the present invention are provided by a multi-fin FINFET device which may include a substrate and a plurality of semiconductor fins extending upwardly from the substrate and being spaced apart along the substrate. Each semiconductor fin may have opposing first and second ends and a medial portion therebetween, and outermost fins of the plurality of semiconductor fins may comprise an epitaxial growth barrier on outside surfaces thereof. The FINFET may further include at least one gate overlying the medial portions of the semiconductor fins, a plurality of raised epitaxial semiconductor source regions between the semiconductor fins adjacent the first ends thereof, and a plurality of raised epitaxial semiconductor drain regions between the semiconductor fins adjacent the second ends thereof. As such, epitaxial growth on the outside surfaces of the outermost fins may be avoided during growth of the raised epitaxial source and drain regions, which may advantageously result in a reduced likelihood of electrical shorting.

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By way of example, the epitaxial growth barrier may comprise a compound comprising a semiconductor and at least one of carbon and fluorine. Furthermore, the plurality of semiconductor fins may comprise silicon, for example. More particularly, the plurality of semiconductor fins may comprise a first set of P-channel fins and a second set of N-channel fins spaced apart from the first set of P-channel fins to define a complementary metal-oxide semiconductor (CMOS) FINFET, and the at least one gate may comprise a respective gate for each of the first set of P-channel fins and the second set of N-channel fins.

The multi-fin FINFET device may further include a gate contact region coupled to the gate and extending upwardly from the substrate and spaced apart from the semiconductor fins. In addition, the multi-fin FINFET device may also include a source contact region coupled to the first ends of the plurality of semiconductor fins, and a drain contact region coupled to the second ends of the plurality of semiconductor fins.

A related method of making a multi-fin FINFET device may include forming a plurality of semiconductor fins extending upwardly from a substrate and being spaced apart along the substrate, where each semiconductor fin has opposing first and second ends and a medial portion therebetween. The method may further include forming at least one gate overlying the medial portions of the semiconductor fins, forming an epitaxial growth barrier on outside surfaces of outermost fins of the plurality of semiconductor fins, forming a plurality of raised epitaxial semiconductor source regions between the semiconductor fins adjacent the first ends thereof, and forming a plurality of raised epitaxial semiconductor drain regions between the semiconductor fins adjacent the second ends thereof.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a perspective view of a CMOS multi-fin FINFET device in accordance with the invention.

FIGS. 2A and 2B are side and top views, respectively, showing formation of the fins of the FINFET of FIG. 1.

FIGS. 3A and 3B are side and top views, respectively, showing formation of tri-gates on the fins of the FINFET of FIG. 1.

FIG. 4 is a side view showing an ion implantation step to form epitaxial growth barriers on outside surfaces of the outermost fins of the FINFET of FIG. 1.

FIGS. 5A and 5B are side and top views, respectively, showing formation of epitaxial source and drain regions of the FINFET of FIG. 1.

FIG. 6 is a flow diagram corresponding to the steps illustrated in FIGS. 2A, 2B, 3A, 3B, 4, 5A, and 5B.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

The present invention will now be described more fully hereinafter with reference to the accompanying drawings, in which preferred embodiments of the invention are shown. This invention may, however, be embodied in many different forms and should not be construed as limited to the embodiments set forth herein. Rather, these embodiments are provided so that this disclosure will be thorough and complete, and will fully convey the scope of the invention to those skilled in the art. Like numbers refer to like elements throughout.

Referring initially to FIGS. 1-5, a multi-fin FINFET device 30 and associated method aspects are first described. In the

illustrated example, the FINFET **30** is a complementary metal oxide semiconductor (CMOS) device including an NFET and a PFET. The FINFET **30** may be configured to provide various devices such as memories, logic gates, etc., using the contact regions described further below. However, it should be noted that non-CMOS configurations may be used in different embodiments as well (i.e., individual NFETs or PFETs).

The FINFET **30** illustratively includes a substrate **31**, which may be a semiconductor substrate (e.g., silicon, germanium, Si/Ge, etc.), a semiconductor on insulator (SOI) substrate, etc. Furthermore, a plurality of semiconductor fins **32n**, **32p** for respective NFET and PFET devices extend upwardly from the substrate **31**, and are laterally spaced apart along the substrate (left to right in FIGS. 2A, 2B). In FIG. 2A, to **5B**, the NFET is on the left and the PFET is on the right. Each semiconductor fin **32n**, **32p** respectively has opposing first and second ends **33a**, **33b** and **34a**, **34b**, and a respective medial portion **35a**, **35b** therebetween (indicated with dashed lines in FIG. 2B). Outermost fins of the plurality of semiconductor fins (i.e., the fins **32n**, **32p** on the far left and right of their respective sets of fins) comprise an epitaxial growth barrier **35n**, **35p** on outside surfaces thereof, as will be described further below.

The FINFET **30** further illustratively includes respective gates **37n**, **37p** for the NFET and PFET, which overlie the respective medial portions **35a**, **35b** of the fins **32n**, **32p**. More particularly, the gates **37n**, **37p** are tri-gate structures, each of which may include an insulator layer and an electrode layer overlying the insulator layer. In addition, a plurality of raised epitaxial semiconductor source regions **38n**, **38p** extend between the semiconductor fins **32n**, **32p** adjacent the first ends **33a**, **34a** thereof, respectively. Moreover, a plurality of raised epitaxial semiconductor drain regions **39n**, **39p** extend between the semiconductor fins **32n**, **32p** adjacent the second ends **33b**, **34b** thereof. The FINFET **30** further illustratively includes gate contact regions **40n**, **40p** respectively coupled to the gates **37n**, **37p** and extending upwardly from the substrate **31** and spaced apart from the semiconductor fins **40n**, **40p** (FIG. 1). Similarly, respective source contact regions **41n**, **41p** are coupled to the first ends **33a**, **34a** of the semiconductor fins **32n**, **32p**, and respective drain contact regions **42n**, **42p** are coupled to the second ends **33b**, **34b** of the semiconductor fins **32n**, **32p**.

As noted above, multi-fin FINFETs are advantageous in that the effective gate width is $2nh$, where n is the number of fins and h is the fin height. Accordingly, wider transistors with higher on-currents may be obtained by using multiple fins. However, when source/drain epitaxial growth is used to merge the fins **32n**, **32p** to lower the external resistance, epitaxial growth will otherwise occur between the two sets of fins. That is, not only is there intra-fin growth of the epitaxial semiconductor material between the fins **32n**, and **32p**, in a typical FINFET integration process there will be inter-fin growth between the two sets of fins, for example. This may otherwise be problematic in that it can cause shorting between the NFET and PFET fins **32n**, **32p**. The above-noted epitaxial growth barriers **36n**, **36p** advantageously help constrain epitaxial growth to intra-fin growth to interior or inner fin surfaces between the fins **32n**, **32p**, and thus reduce a likelihood of shorting between the NFET and PFET devices.

An example approach for fabricating the FINFET **30** with the epitaxial growth barriers **36n**, **36p** will now be described further with reference to the flow diagram **60** of FIG. 6. Beginning at Block **61**, the semiconductor (e.g., silicon, germanium, Si/Ge, etc.) fins **32n**, **32p** are formed extending upwardly from the substrate **31** and are spaced apart along the

substrate, as noted above, at Block **62** (FIGS. 2A and 2B). The gates **37n**, **37p** are then formed overlying the medial portions **35a**, **35b** of the semiconductor fins **32n**, **32p**, respectively, at Block **63**. Again, with a tri-gate structure, the gates **37n**, **37p** (which respectively include an insulator layer and a gate electrode layer) will wrap around the top and side surfaces of the fins **32n**, **32p**, as seen in FIGS. 3A, 3B.

The method further includes forming the epitaxial growth barriers **36n**, **36p** on outside surfaces of the outermost fins from the sets of fins **32n**, **32p**, as noted above, at Block **64**. More particularly, this may be done by performing an ion implantation at an angle α offset from normal to the substrate **31**, as represented by the dashed arrows in FIG. 4. More particularly, a dual-angled implant/reactive ion etch (RIE) may be performed using Carbon-Fluorine (e.g., CF_4) or other suitable gases. As a result, the epitaxial growth barriers **36n**, **36p** will comprise a compound including the semiconductor fin material (e.g., silicon, etc.), carbon and/or fluorine components. The epitaxial growth barriers **36n**, **36p** will appear as a film or coating, and they will inhibit grow of epitaxial semiconductor material during formation of the raised source regions **38n**, **38p** and drain regions **39n**, **39p**, at Blocks **65-66** (FIGS. 5A, 5B), which illustratively concludes the method shown in FIG. 6 (Block **67**).

The angle of implantation α may be chosen so as not to be too steep, and thereby allow ion penetration too deep between the fins **32n** or **32p**, yet not too shallow so that the outside surfaces of the sets of fins facing one another do not get coated on the bottom (which would allow excessive inter-fin epitaxial growth that could result in shorting between the NFET and PFET devices, as described above). Generally speaking, the angle of implantation α may be in a range of 30 to 60 degrees, depending upon the height and lateral spacing of the fins **32n**, **32p** which are used in a given embodiment. Because the inner surfaces of the fins **32n**, **32p** are blocked from ion bombardment by the adjacent fins, these inner surfaces will have relatively little impact or damage from the implantation, and will thereby still allow for the subsequent epitaxial source and drain growth. With proper angle selection only a small portion of these inner surfaces near the tops of the fins **32n**, **32p** will be impacted by the implantation and thereby have epitaxial growth barriers **36n**, **36p** formed thereon, as shown in FIGS. 4 and 5A.

It will therefore be appreciated that that the above-described approach may be relatively easy to implement, in that an additional step (i.e., the ion implantation) may be added to a multi-fin FINFET fabrication process to provide the epitaxial growth barriers **36n**, **36p** and reduce the likelihood of shorting in the finished device. That is, the above-described approach advantageously allows for relatively high density multi-fin configurations to be fabricated without the epitaxial merging between the NFETs and PFETs. The epitaxial growth barriers **36n**, **36p** may provide desired retardation of epitaxial growth, so that this growth is confined to the inner surfaces of the fins **32n**, **32p** where desired.

Many modifications and other embodiments of the invention will come to the mind of one skilled in the art having the benefit of the teachings presented in the foregoing descriptions and the associated drawings. Therefore, it is understood that the invention is not to be limited to the specific embodiments disclosed, and that modifications and embodiments are intended to be included within the scope of the appended claims.

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That which is claimed is:

1. A multi-fin FINFET device comprising:

a substrate;

a plurality of semiconductor fins extending upwardly from said substrate and being spaced apart along the substrate, each semiconductor fin having opposing first and second ends and a medial portion therebetween, outermost fins of said plurality of semiconductor fins comprising an epitaxial growth barrier on outside and top surfaces thereof and on portions of inner surfaces thereof adjacent the top surfaces;

at least one gate overlying the medial portions of said semiconductor fins;

a plurality of raised epitaxial semiconductor source regions between said semiconductor fins adjacent the first ends thereof; and

a plurality of raised epitaxial semiconductor drain regions between said semiconductor fins adjacent the second ends thereof.

2. The multi-fin FINFET device of claim **1** wherein said epitaxial growth barrier comprises a compound comprising a semiconductor and at least one of carbon and fluorine.

3. The multi-fin FINFET device of claim **1** wherein said plurality of semiconductor fins comprise silicon.

4. The multi-fin FINFET device of claim **1** wherein said plurality of semiconductor fins comprises a first set of P-channel fins and a second set of N-channel fins spaced apart from the first set of P-channel fins to define a complementary metal-oxide semiconductor (CMOS) FINFET.

5. The multi-fin FINFET device of claim **4** wherein said at least one gate comprises a respective gate for each of said first set of P-channel fins and said second set of N-channel fins.

6. The multi-fin FINFET device of claim **1** further comprising a gate contact region coupled to said gate and extending upwardly from said substrate and spaced apart from said semiconductor fins.

7. The multi-fin FINFET device of claim **1** further comprising:

a source contact region coupled to the first ends of said plurality of semiconductor fins; and

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a drain contact region coupled to the second ends of said plurality of semiconductor fins.

8. A multi-fin FINFET device comprising:

a substrate;

a plurality of silicon fins extending upwardly from said substrate and being spaced apart along the substrate, each silicon fin having opposing first and second ends and a medial portion therebetween, outermost fins of said plurality of silicon fins comprising an epitaxial growth barrier on outside and top surfaces thereof and on portions of inner surfaces thereof adjacent the top surfaces, and said epitaxial growth barrier comprising a compound comprising silicon and at least one of carbon and fluorine;

at least one gate overlying the medial portions of said silicon fins;

a plurality of raised epitaxial semiconductor source regions between said silicon fins adjacent the first ends thereof; and

a plurality of raised epitaxial semiconductor drain regions between said silicon fins adjacent the second ends thereof.

9. The multi-fin FINFET device of claim **8** wherein said plurality of silicon fins comprises a first set of P-channel fins and a second set of N-channel fins spaced apart from the first set of P-channel fins to define a complementary metal-oxide semiconductor (CMOS) FINFET.

10. The multi-fin FINFET device of claim **9** wherein said at least one gate comprises a respective gate for each of said first set of P-channel fins and said second set of N-channel fins.

11. The multi-fin FINFET device of claim **8** further comprising a gate contact region coupled to said gate and extending upwardly from said substrate and spaced apart from said silicon fins.

12. The multi-fin FINFET device of claim **8** further comprising:

a source contact region coupled to the first ends of said plurality of silicon fins; and

a drain contact region coupled to the second ends of said plurality of silicon fins.

* * * * *